

CLEAN VERSION OF CLAIMS

1. A high-frequency coil comprising:
a dielectric substrate; and
a coil formed of at least one conductive layer embedded in a surface of said dielectric substrate, and side surfaces of said coil having substantially vertical walls as a result of plating the coil on a temporary base layer that is removed.

2. The high-frequency coil device as claimed in claim 1, wherein said coil has portions which have a gap between a bottom surface of the coil and the substrate.

10. The high-frequency coil of claim 6, wherein the gold layer has a thickness of .3 to 5 μm .